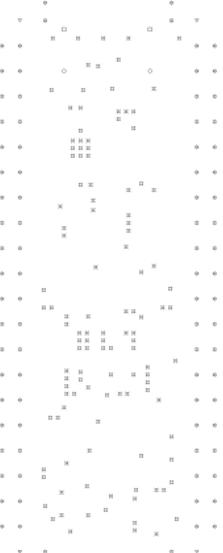
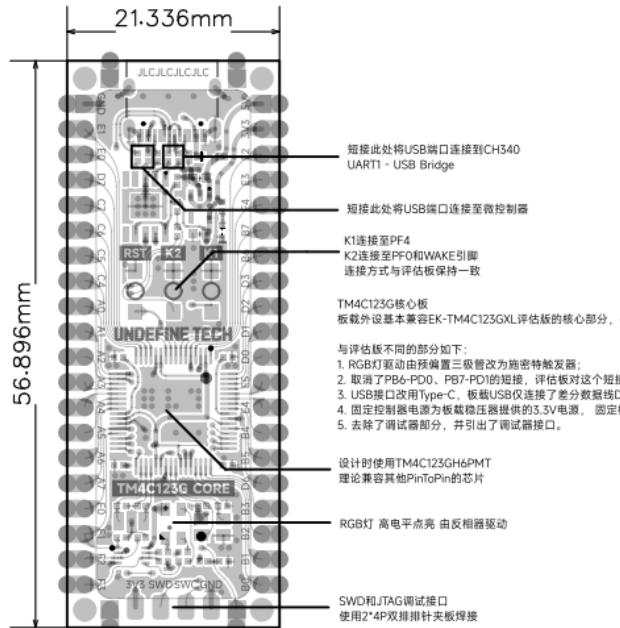


| Mark | Count | Size | Plated | Shape | Via/Pad | Pad Shape | Layer Pair |
|------|-------|-----------------------------|--------|-------|---------|-----------|------------------------|
| □ | 2 | 27.6x55.1mil(0.700x1.400mm) | PTH | Slot | Pad | Oval | Top Layer-Bottom Layer |
| ○ | 2 | 27.6x66.9mil(0.700x1.700mm) | PTH | Slot | Pad | Oval | Top Layer-Bottom Layer |
| ▽ | 4 | 78.7x78.7mil(2.000x2.000mm) | PTH | Round | Pad | Round | Top Layer-Bottom Layer |
| ☆ | 88 | 35.4x35.4mil(0.900x0.900mm) | PTH | Round | Pad | (Mixed) | Top Layer-Bottom Layer |
| ❖ | 125 | 12.0mil(0.305mm) | PTH | Round | Via | | Top Layer-Bottom Layer |





- 与评估板不同的部分如下：
1. RGB灯驱动由预偏置三极管改为施密特触发器；
 2. 取消了PB6-PD0、PB7-PD1的短接，评估板对这个短接的描述是“兼容MSP430”；
 3. USB接口改用Type-C，板载USB仅连接了差分数据线DP和DM，没有连接ID和电源信号；
 4. 固定控制器电源为板载稳压器提供的3.3V电源，固定模拟参考电压为板载稳压器的输出电压
 5. 去除了调试窗口部分，并引出了调试器接口。